

SEMICONDUCTOR DEVICE

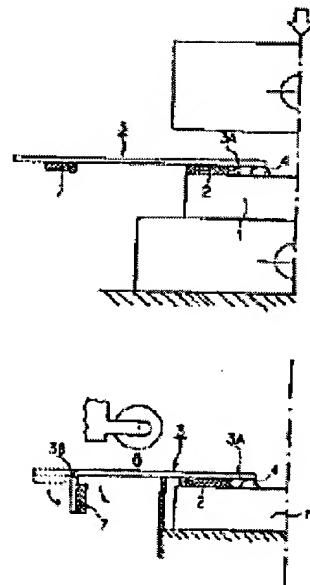
Patent number: JP4085837
Publication date: 1992-03-18
Inventor: TSUBOSAKI KUNIHIRO; TANIMOTO MICHIO; NISHI KUNIHIKO; ICHITANI MASAHIRO; KOIKE SHUNJI; SUZUKI KAZUNARI; KIMOTO RYOSUKE
Applicant: HITACHI LTD.; HITACHI MICROCOMPUTER ENG
Classification:
- **international:** H01L21/60; H01L23/50
- **european:**
Application number: JP19900198462 19900726
Priority number(s): JP19900198462 19900726

[Report a data error here](#)

Abstract of JP4085837

PURPOSE: To obtain an ultra-thin package which can contain a large semiconductor chip by a constitution in which a lead is secured onto the circuit forming face of a semiconductor through an insulating adhesive layer and extended to the rear surface of the semiconductor chip to be secured in place through an insulating adhesive layer.

CONSTITUTION: A lead frame provided with an insulating adhesive film 2 is mounted on the circuit forming face of a semiconductor chip 1 having a solder bump electrode 4 and press bonded by means of a heating block thus adhering the insulating adhesive film 2 onto the circuit forming face of the semiconductor chip 1 and bonding the inner lead 3A of a lead 3 to the bump electrode 4 of the semiconductor chip 1. The outer lead 3B of the lead 3 is then bent at the tip thereof and further bent in parallel with the side of the semiconductor chip 1 by means of a roller or the like thus thermocompressing an insulating adhesive film 7 to the rear surface of the semiconductor chip 1. A resin block member 5 is then formed on the circuit forming face of the semiconductor chip 1, liquid resin is dripped and cured, thus completing a package. According to the constitution, the package can be fabricated with dimensions substantially same as those of the semiconductor chip.



BEST AVAILABLE COPY

Data supplied from the **esp@cenet** database - Worldwide